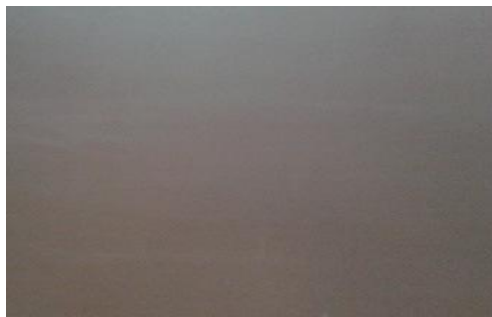


PHENOLIC PAPER LAMINATE

TECHNICAL DATA SHEET
REV.02 - 05/02/2019



DESCRIPTION:

Paper base laminate with phenolic resin binder suitable for hot punching up to and including 3 mm.

TECHNICAL SPECIFICATIONS:

	UNIT	VALUE	NORM
Density	g/cm ³	1,38	ISO 1183
Water Absorption mm1	mg	450	IEC 60893-2
Thermal classification	°C	E (120°C)	IEC 60216
Self-extinguishing		HB	UL 94
Thermal Conductivity	W/mK	0,25	ISO 8302
Expansion Coefficient	10 ⁻⁶ /K	-	VDE 0304/VSM
Silicone Resin Content	%	-	IEC 371-2
Mica Content	%	-	IEC 371-2
Thickness	mm	1 up to 30	
MECHANICAL PROPERTIES			
Flexural Strength (perp.)	MPa	80	ISO 178
Charpy Impact Strength	KJ/m ²	-	ISO 179
Tensile Strength	MPa	-	ISO 527
Compressive Strength	MPa	-	ISO 604
Bonding Strength //	N	-	CEI
Modulus Of Elasticity	MPa	-	ISO 178
DIELECTRICAL PROPERTIES			
Insulation Resistance	MOhm	-	ISO 60167
Dielectric Strength //	KV	30	ISO 60243-1
Dielectric Strength (perp.)	KV/mm	1	ISO 60243-1
Tracking Resistance	V	-	IEC 60112
Arc Resistance	S	-	ASTM D495
Dissipation Factor at 1MHz		-	IEC 60250
Dielectric Constant (permittivity) at 1MHz		-	IEC 60250